

ENGINEERING PRACTICE STUDY

PROJECT NUMBER: 5998-2008-031

TITLE:

Review of Non-Government Standard (NGS) IPC-4562
to Determine the Validity of Its DoD Adoption.

06 June 2008

FINAL REPORT

Prepared by:

David Corbett

ATTCH 1

I. **OBJECTIVES:** The objective of this study was to review reference document sections of all Federal Stock Classes (FSC) documents for guidance on retaining non-Government standard IPC-4562 as viable and appropriate for citing in electronic component standardization documents.

II. **BACKGROUND:** IPC-4562, “Metal Foil for Printed Wiring Applications”, was adopted on 26 February 2003 and the DoD notice of adoption has not been revised since that date. IPC-4562 was developed and published its non-Government standard body (NGSB), the IPC – Association Connecting Electronics Industries. The NGSB committee responsible for IPC-4562 meets regularly to maintain and keep current its contents. DSCC attends many of these meetings and makes comments to drafts in order to represent the DoDs position regarding IPC-4562. This study is part of a 5-year review of the DoD adoption notice for validity and accuracy, since the NGS document has already been adopted for use by the DoD.

III. **RESULTS:** A review using ASSIST to search for use of IPC-4562 within DoD documents resulted in no direct references by DoD standardization documents. This fact is acceptable. IPC-4562 is primarily used as a reference on printed board detail drawings that support the performance specifications MIL-PRF-31032, MIL-PRF-55110, and MIL-P-50884. A review of the actual notice of adoption that is on the ASSIST web site uncovered mistakes in some of the information regarding out of date information for both the NGSB and the DSCC point of contact.

IV. **CONCLUSION:** Based on its usage by design and acquiring activities, IPC-4562 is a valued acquisition document that benefits the DoD standardization program.

V. **RECOMMENDATION:** IPC-4562, “Metal Foil for Printed Wiring Applications”, should continue to be available for citing by DoD standardization documents and for acquiring activities. Therefore, the adoption notice for IPC-4562 shall be retained as an active, valid document. An updated notice of adoption with should be forwarded to DAPS with current NGSB and DoD contact data.

ADOPTION NOTICE

IPC-4562, "Metal foil for Printed Wiring Applications", was adopted on 26-FEB-03 for use by the Department of Defense (DoD). Proposed changes by DoD activities must be submitted to the DoD Adopting Activity: Defense Supply Center Columbus, P.O. Box 3990, Attn: DSCC-VAI, Columbus, OH 43216-5000. Copies of this document may be purchased from the Institute for Interconnecting and Packaging Electronic Circuits, 2215 Sanders Road, Northbrook, IL 60062-6135. <http://www.ipc.org/>

Custodians:

Army - CR
Navy - EC
Air Force - 11
DLA - CC

Adopting Activity:

DLA - CC

Reviewer Activities:

Army - MI

FSC 5998

DISTRIBUTION STATEMENT A: Approved for public release; distribution is unlimited.

ADOPTION NOTICE

IPC-4562, "Metal Foil for Printed Wiring Applications", was adopted on ~~26 FEB 03~~ 26 February 2003 for use by the Department of Defense (DoD). Proposed changes by DoD activities must be submitted to the DoD Adopting Activity: Defense Logistics Agency, Defense Supply Center Columbus, P.O. Box 3990, ATTN: DSCC-VA/VAC, Columbus, OH ~~43216-5000~~ 43218-3990. Copies of this document standard may be purchased from the ~~Institute for Interconnecting and Packaging Electronic Circuits, 2215 Sanders Road, Northbrook, IL 60062-6135~~ IPC - Association Connecting Electronics Industry (IPC), 3000 Lakeside Drive, Suite 309 S, Bannockburn, IL 60015-1249 or <http://www.ipc.org>.

Custodians:

Army - CR
Navy - EC
Air Force - 11
DLA - CC

Preparing activity:
DLA - CC

Project: 5998-0136-03

Review activities:

Air Force - MI

NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at <http://assist.daps.dla.mil/>.